

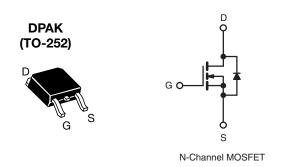
Vishay Siliconix

COMPLIANT HALOGEN

FREE

E Series Power MOSFET

PRODUCT SUMMARY			
V _{DS} (V) at T _J max.	700		
R _{DS(on)} max. at 25 °C (Ω)	V _{GS} = 10 V	0.9	
Q _g max. (nC)	34		
Q _{gs} (nC)	4		
Q _{gd} (nC)	8		
Configuration	Single		



FEATURES

- Low figure-of-merit (FOM) Ron x Qq
- Low input capacitance (Ciss)
- Reduced switching and conduction losses
- Ultra low gate charge (Q_q)
- Avalanche energy rated (UIS)
- Material categorization: for definitions of compliance please see <u>www.vishav.com/doc?99912</u>

APPLICATIONS

- Server and telecom power supplies
- Switch mode power supplies (SMPS)
- Power factor correction power supplies (PFC)
- Lighting
 - High-intensity discharge (HID)
 - Fluorescent ballast lighting
- Industrial
 - Welding
 - Induction heating
 - Motor drives
 - Battery chargers
 - Renewable energy
 - Solar (PV inverters)

ORDERING INFORMATION		
Package	DPAK (TO-252)	
Lead (Pb)-free and Halogen-free	SiHD6N62E-GE3	

ABSOLUTE MAXIMUM RATINGS (T _C :	= 25 °C, unl	ess otherwis	se noted)		
PARAMETER			SYMBOL	LIMIT	UNIT
Drain-Source Voltage			V_{DS}	620	V
Gate-Source Voltage			V_{GS}	± 30	
Continuous Drain Current (T. 150 °C)	V _{GS} at 10 V	T _C = 25 °C		6	
Continuous Drain Current (T _J = 150 °C)	V_{GS} at 10 V $T_C = 100 ^{\circ}C$	I _D	4	Α	
Pulsed Drain Current ^a			I _{DM}	12	1
Linear Derating Factor				0.63	W/°C
Single Pulse Avalanche Energy ^b			E _{AS}	88	mJ
Maximum Power Dissipation			P_{D}	78	W
Operating Junction and Storage Temperature Range		T _J , T _{stg}	-55 to +150	°C	
Drain-Source Voltage Slope T _J = 125 °C		dV/dt	37	\//	
Reverse Diode dV/dt ^d			12	- V/ns	
Soldering Recommendations (Peak Temperature) c for 10 s			300	°C	

Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature.
- b. V_{DD} = 50 V, starting T_J = 25 °C, L = 28.2 mH, R_g = 25 Ω , I_{AS} = 2.5 A.
- c. 1.6 mm from case.
- d. $I_{SD} \le I_D$, $dI/dt = 100 \text{ A/}\mu\text{s}$, starting $T_J = 25 \,^{\circ}\text{C}$.



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THERMAL RESISTANCE RATINGS				
PARAMETER	SYMBOL	TYP.	MAX.	UNIT
Maximum Junction-to-Ambient	R _{thJA}	-	62	°C/W
Maximum Junction-to-Case (Drain)	R_{thJC}	-	1.6	C/VV

PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
Static		-					•
Drain-Source Breakdown Voltage	V _{DS}	V _{GS} =	= 0 V, I _D = 250 μA	620	-	-	V
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	Reference	e to 25 °C, I _D = 1 mA	-	0.76	-	V/°C
Gate-Source Threshold Voltage (N)	V _{GS(th)}	V _{DS} =	= V _{GS} , I _D = 250 μA	2	-	4	V
		,	V _{GS} = ± 20 V	-	-	± 100	nA
Gate-Source Leakage	I_{GSS}		V _{GS} = ± 30 V	-	-	± 1	μΑ
			= 620 V, V _{GS} = 0 V	-	-	1	
Zero Gate Voltage Drain Current	I _{DSS}		/, V _{GS} = 0 V, T _J = 125 °C	-	-	10	μA
Drain-Source On-State Resistance	R _{DS(on)}	V _{GS} = 10 V	I _D = 3 A	-	0.78	0.90	Ω
Forward Transconductance	9fs	V _{DS}	= 30 V, I _D = 3 A	-	1.8	-	S
Dynamic					1	1	
Input Capacitance	C _{iss}	V _{GS} = 0 V,		-	578	-	
Output Capacitance	Coss		/ _{DS} = 100 V,	-	36	-	1
Reverse Transfer Capacitance	C _{rss}	1	f = 1 MHz		4	-	1
Effective Output Capacitance, Energy Related ^a	C _{o(er)}			-	31	-	pF
Effective Output Capacitance, Time Related ^b	C _{o(tr)}	$V_{DS} = 0.0$	$V_{DS} = 0 \text{ V to } 496 \text{ V}, V_{GS} = 0 \text{ V}$		87	-	
Total Gate Charge	Qg			-	17	34	
Gate-Source Charge	Q _{gs}	$V_{GS} = 10 \text{ V}$ $I_D = 3 \text{ A}, V_{DS} = 496 \text{ V}$		-	4	-	nC
Gate-Drain Charge	Q _{gd}	1		-	8	-	
Turn-On Delay Time	t _{d(on)}	V _{DD} = 496 V, I _D = 3 A,		-	12	24	
Rise Time	t _r			-	10	20	no
Turn-Off Delay Time	t _{d(off)}	00	$V_{GS} = 10 \text{ V}, R_{g} = 9.1 \Omega$		22	44	ns
Fall Time	t _f			-	16	32	
Gate Input Resistance	R_g	f = 1 MHz, open drain		-	1.3	-	Ω
Drain-Source Body Diode Characteristic	s						
Continuous Source-Drain Diode Current	I _S	MOSFET symbol showing the integral reverse p - n junction diode		-	-	7	
Pulsed Diode Forward Current	I _{SM}			-	-	12	A
Diode Forward Voltage	V _{SD}	T _J = 25 °C, I _S = 3 A, V _{GS} = 0 V		-	0.9	1.2	V
Reverse Recovery Time	t _{rr}	T _J = 25 °C, I _F = I _S = 3 A, dl/dt = 100 A/μs, V _R = 400 V		-	190	-	ns
Reverse Recovery Charge	Q _{rr}			-	1.3	-	μC
Reverse Recovery Current	I _{RRM}				11		A

Notes

- a. $C_{oss(er)}$ is a fixed capacitance that gives the same energy as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS} . b. $C_{oss(tr)}$ is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS} .



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

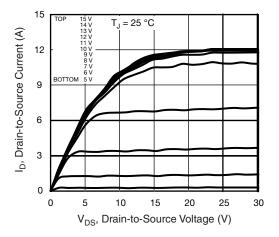


Fig. 1 - Typical Output Characteristics

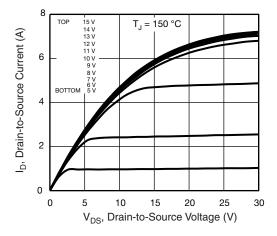


Fig. 2 - Typical Output Characteristics

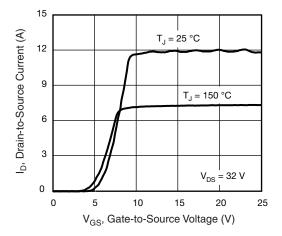


Fig. 3 - Typical Transfer Characteristics

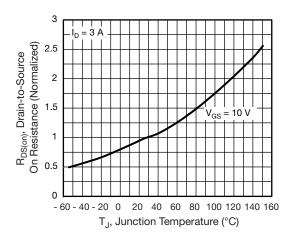


Fig. 4 - Normalized On-Resistance vs. Temperature

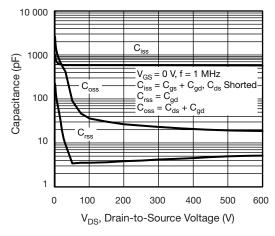


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

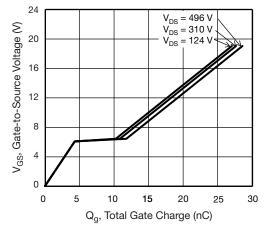


Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage



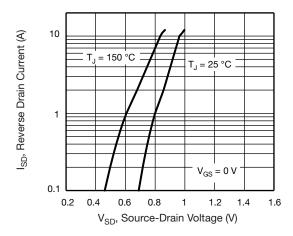


Fig. 7 - Typical Source-Drain Diode Forward Voltage

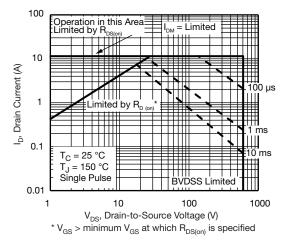


Fig. 8 - Maximum Safe Operating Area

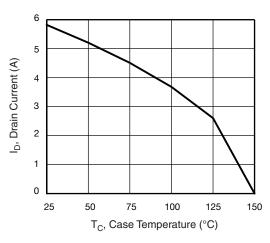


Fig. 9 - Maximum Drain Current vs. Case Temperature

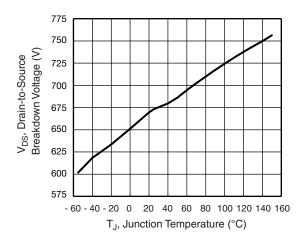


Fig. 10 - Temperature vs. Drain-to-Source Voltage

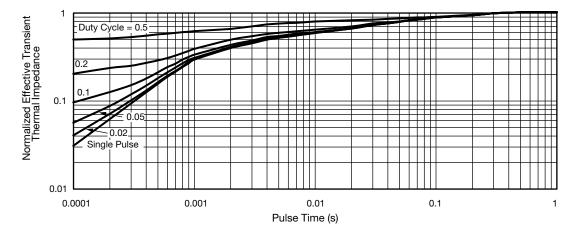


Fig. 11 - Normalized Thermal Transient Impedance, Junction-to-Case

www.vishay.com

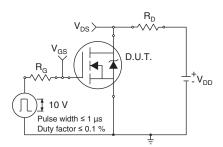


Fig. 12 - Switching Time Test Circuit

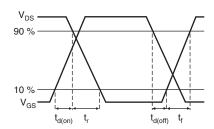


Fig. 13 - Switching Time Waveforms

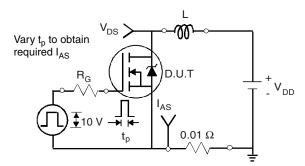


Fig. 14 - Unclamped Inductive Test Circuit

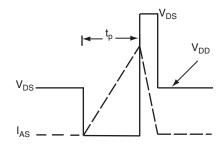


Fig. 15 - Unclamped Inductive Waveforms

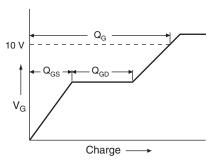


Fig. 16 - Basic Gate Charge Waveform

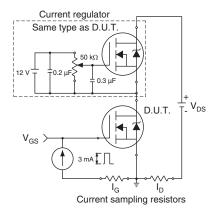
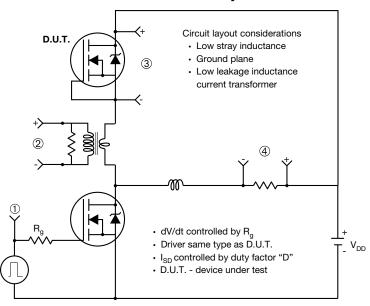


Fig. 17 - Gate Charge Test Circuit



Peak Diode Recovery dV/dt Test Circuit



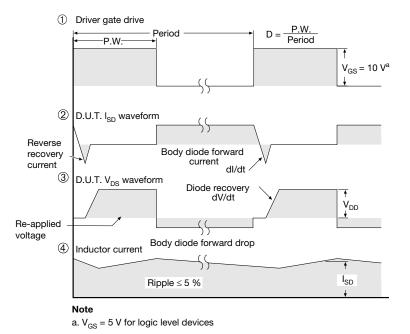


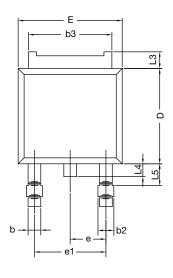
Fig. 18 - For N-Channel

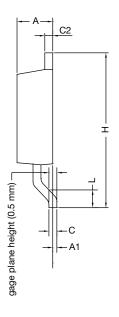
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TO-252AA Case Outline

VERSION 1: FACILITY CODE = Y







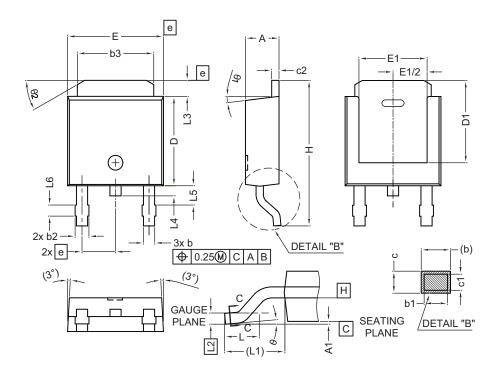
	MILLIMETERS		
DIM.	MIN.	MAX.	
А	2.18	2.38	
A1	-	0.127	
b	0.64	0.88	
b2	0.76	1.14	
b3	4.95	5.46	
С	0.46	0.61	
C2	0.46	0.89	
D	5.97	6.22	
D1	4.10	-	
Е	6.35	6.73	
E1	4.32	=	
Н	9.40	10.41	
е	2.28 BSC		
e1	4.56 BSC		
L	1.40	1.78	
L3	0.89	1.27	
L4	-	1.02	
L5	1.01	1.52	

Note

• Dimension L3 is for reference only



VERSION 2: FACILITY CODE = N



	MILLIMETERS		
DIM.	MIN.	MAX.	
А	2.18	2.39	
A1	-	0.13	
b	0.65	0.89	
b1	0.64	0.79	
b2	0.76	1.13	
b3	4.95	5.46	
С	0.46	0.61	
c1	0.41	0.56	
c2	0.46	0.60	
D	5.97	6.22	
D1	5.21	-	
Е	6.35	6.73	
E1	4.32 -		
е	2.29 BSC		
Н	9.94	10.34	

	MILLIMETERS		
DIM.	MIN.	MAX.	
L	1.50	1.78	
L1	2.74	ł ref.	
L2	0.51	BSC	
L3	0.89	1.27	
L4	-	1.02	
L5	1.14	1.49	
L6	0.65	0.85	
θ	0°	10°	
θ1	0°	15°	
θ2	25°	35°	

Notes

- Dimensioning and tolerance confirm to ASME Y14.5M-1994
- All dimensions are in millimeters. Angles are in degrees
- Heat sink side flash is max. 0.8 mm
- Radius on terminal is optional

ECN: E22-0399-Rev. R, 03-Oct-2022

DWG: 5347



RECOMMENDED MINIMUM PADS FOR DPAK (TO-252)



Recommended Minimum Pads Dimensions in Inches/(mm)

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APPLICATION NOTE



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